

512K x 16 HIGH-SPEED ASYNCHRONOUS CMOS STATIC RAM WITH 3.3V SUPPLY

OCTOBER 2009

FEATURES

- High-speed access times:
 8, 10, 20 ns
- High-performance, low-power CMOS process
- Multiple center power and ground pins for greater noise immunity
- Easy memory expansion with CE and OE options
- CE power-down
- Fully static operation: no clock or refresh required
- TTL compatible inputs and outputs
- Single power supply
 VDD 1.65V to 2.2V (IS61WV51216ALL)
 speed = 20ns for VDD 1.65V to 2.2V
 VDD 2.4V to 3.6V (IS61/64WV51216BLL)
 speed = 10ns for VDD 2.4V to 3.6V
 speed = 8ns for VDD 3.3V + 5%
- Packages available:
 - 48-ball miniBGA (9mm x 11mm)
 - 44-pin TSOP (Type II)
- Industrial and Automotive Temperature Support
- Lead-free available
- Data control for upper and lower bytes

DESCRIPTION

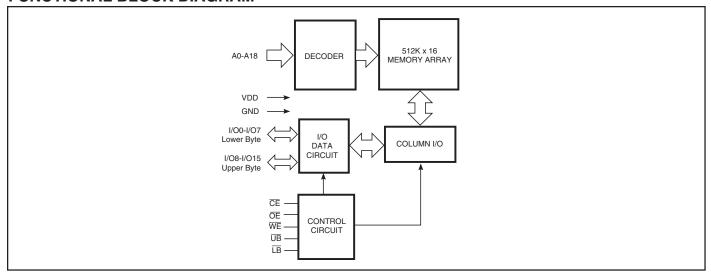
The *ISSI* IS61WV51216ALL/BLL and IS64WV51216BLL are high-speed, 8M-bit static RAMs organized as 512K words by 16 bits. It is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields high-performance and low power consumption devices.

When $\overline{\text{CE}}$ is HIGH (deselected), the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs, $\overline{\textbf{CE}}$ and $\overline{\textbf{OE}}$. The active LOW Write Enable ($\overline{\textbf{WE}}$) controls both writing and reading of the memory. A data byte allows Upper Byte ($\overline{\textbf{UB}}$) and Lower Byte ($\overline{\textbf{LB}}$) access.

The device is packaged in the JEDEC standard 44-pin TSOP Type II and 48-pin Mini BGA (9mm x 11mm).

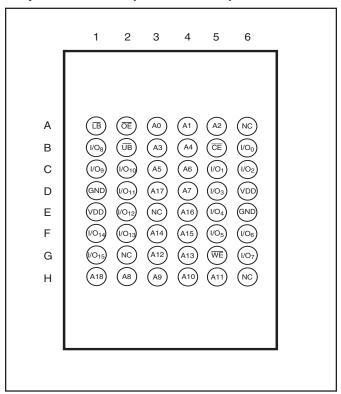
FUNCTIONAL BLOCK DIAGRAM



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48-pin mini BGA (9mmx11mm)



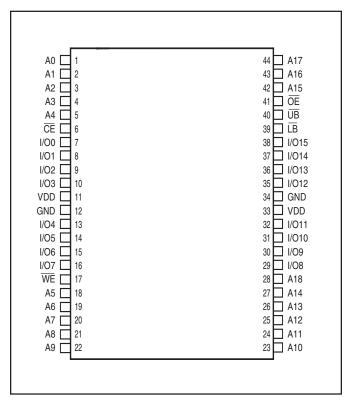
PIN DESCRIPTIONS

A0-A18	Address Inputs	
I/O0-I/O15	Data Inputs/Outputs	
CE	Chip Enable Input	
ŌĒ	Output Enable Input	
WE	Write Enable Input	
LB	Lower-byte Control (I/O0-I/O7)	
UB	Upper-byte Control (I/O8-I/O15)	
NC	No Connection	
V _{DD}	Power	
GND	Ground	



PIN CONFIGURATIONS

44-Pin TSOP (Type II)



PIN DESCRIPTIONS

A0-A18	Address Inputs
I/O0-I/O15	Data Inputs/Outputs
CE	Chip Enable Input
ŌĒ	Output Enable Input
WE	Write Enable Input
LB	Lower-byte Control (I/O0-I/O7)
UB	Upper-byte Control (I/O8-I/O15)
NC	No Connection
VDD	Power
GND	Ground



TRUTH TABLE

						I/O	PIN	_
Mode	WE	Œ	ŌĒ	LB	UB	I/O0-I/O7	I/O8-I/O15	V DD Current
Not Selected	Х	Н	Х	Х	Х	High-Z	High-Z	ISB1, ISB2
Output Disabled	H X	L L	H X	X H	X H	High-Z High-Z	High-Z High-Z	Icc
Read	H H H	L L L	L L L	L H L	H L L	Douт High-Z Douт	High-Z Douт Douт	Icc
Write	L L L	L L L	X X X	L H L	H L L	Dın High-Z Dın	High-Z Dın Dın	Icc

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Parameter	Value	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to V _{DD} + 0.5	V
VDD	VDD Relates to GND	-0.3 to 4.0	V
Тѕтс	Storage Temperature	-65 to +150	°C
Рт	Power Dissipation	1.0	W

Notes:

CAPACITANCE(1,2)

Symbol	Parameter	Conditions	Max.	Unit
Cin	Input Capacitance	VIN = 0V	6	pF
CI/O	Input/Output Capacitance	Vout = 0V	8	pF

- 1. Tested initially and after any design or process changes that may affect these parameters.
- 2. Test conditions: $T_A = 25^{\circ}C$, f = 1 MHz, $V_{DD} = 3.3V$.

Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage
to the device. This is a stress rating only and functional operation of the device at these or any other
conditions above those indicated in the operational sections of this specification is not implied. Exposure
to absolute maximum rating conditions for extended periods may affect reliability.



OPERATING RANGE (VDD) (IS61WV51216ALL)

Range	Ambient Temperature	V _{DD} (20 ns)	
Commercial	0°C to +70°C	1.65V-2.2V	
Industrial	–40°C to +85°C	1.65V-2.2V	
Automotive	-40°C to +125°C	1.65V-2.2V	

OPERATING RANGE (VDD) (IS61WV51216BLL)(1)

Range	Ambient Temperature	V _{DD} (8 n s)	VDD (10 ns)	
Commercial	0°C to +70°C	3.3V <u>+</u> 5%	2.4V-3.6V	
Industrial	-40°C to +85°C	3.3V <u>+</u> 5%	2.4V-3.6V	

Note

OPERATING RANGE (VDD) (IS64WV51216BLL)

Range	Ambient Temperature	V _{DD} (10 ns)	
Automotive	-40°C to +125°C	2.4V-3.6V	

^{1.} When operated in the range of 2.4V-3.6V, the device meets 10ns. When operated in the range of $3.3V \pm 5\%$, the device meets 8ns.



DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

 $V_{DD} = 3.3V \pm 5\%$

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Vон	Output HIGH Voltage	$V_{DD} = Min., I_{OH} = -4.0 \text{ mA}$	2.4	_	V
Vol	Output LOW Voltage	V _{DD} = Min., I _{OL} = 8.0 mA	_	0.4	V
VIH	Input HIGH Voltage		2	VDD + 0.3	V
VIL	Input LOW Voltage ⁽¹⁾		-0.3	8.0	V
ILI	Input Leakage	$GND \le V_{IN} \le V_{DD}$	-1	1	μA
ILO	Output Leakage	GND ≤ Vouт ≤ Vdd, Outputs Disabled	-1	1	μA

Note:

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

 $V_{DD} = 2.4V - 3.6V$

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Vон	Output HIGH Voltage	V _{DD} = Min., Iон = -1.0 mA	1.8	_	V
Vol	Output LOW Voltage	VDD = Min., IoL = 1.0 mA	_	0.4	V
VIH	Input HIGH Voltage		2.0	V _{DD} + 0.3	V
VIL	Input LOW Voltage(1)		-0.3	0.8	V
ILI	Input Leakage	GND ≤ VIN ≤ VDD	-1	1	μA
ILO	Output Leakage	GND ≤ Vo∪t ≤ Vdd, Outputs Disabled	-1	1	μΑ

Note:

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

 $V_{DD} = 1.65V-2.2V$

Symbol	Parameter	Test Conditions	V _{DD}	Min.	Max.	Unit
Vон	Output HIGH Voltage	Iон = -0.1 mA	1.65-2.2V	1.4	_	V
Vol	Output LOW Voltage	IoL = 0.1 mA	1.65-2.2V	_	0.2	V
ViH	Input HIGH Voltage		1.65-2.2V	1.4	VDD + 0.2	V
VIL ⁽¹⁾	Input LOW Voltage		1.65-2.2V	-0.2	0.4	V
ILI	Input Leakage	GND ≤ VIN ≤ VDD		-1	1	μΑ
ILO	Output Leakage	GND ≤ Vout ≤ Vdd, O	utputs Disabled	– 1	1	μΑ

VIL (min.) = -0.3V DC; VIL (min.) = -2.0V AC (pulse width < 10 ns). Not 100% tested.
 VIH (max.) = VDD + 0.3V DC; VIH (max.) = VDD + 2.0V AC (pulse width < 10 ns). Not 100% tested.

VIL (min.) = -0.3V DC; VIL (min.) = -2.0V AC (pulse width < 10 ns). Not 100% tested.
 VIH (max.) = VDD + 0.3V DC; VIH (max.) = VDD + 2.0V AC (pulse width < 10 ns). Not 100% tested.

VIL (min.) = -0.3V DC; VIL (min.) = -2.0V AC (pulse width < 10 ns). Not 100% tested.
 VIH (max.) = VDD + 0.3V DC; VIH (max.) = VDD + 2.0V AC (pulse width < 10 ns). Not 100% tested.



AC TEST CONDITIONS (HIGH SPEED)

Parameter	Unit (2.4V-3.6V)	Unit (3.3V <u>+</u> 5%)	Unit (1.65V-2.2V)
Input Pulse Level	0.4V to VDD-0.3V	0.4V to VDD-0.3V	0.4V to VDD-0.2V
Input Rise and Fall Times	1.5ns	1.5ns	1.5ns
Input and Output Timing and Reference Level (VRef)	V _{DD} /2	VDD/2 + 0.05	V _{DD} /2
Output Load	See Figures 1 and 2	See Figures 1 and 2	See Figures 1 and 2

AC TEST LOADS

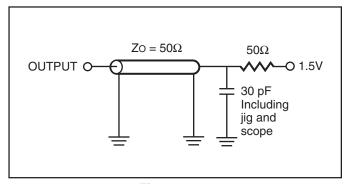


Figure 1.

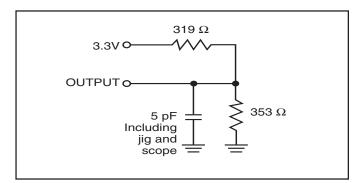


Figure 2.



POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

					8	-1	0	-2	20	
Symbol	Parameter	Test Conditions		Min.	Max.	Min.	Max.	Min.	Max.	Unit
Icc	VDD Dynamic Operating	V _{DD} = Max.,	Com.	_	110	_	90	_	50	mA
	Supply Current	IOUT = 0 mA, f = fMAX	Ind.	_	115	_	95	_	60	
			Auto.	_	_	_	140	_	100	
			typ.(2)			60)			
lcc1	Operating	V _{DD} = Max.,	Com.	_	85	_	85	_	45	mA
	Supply Current	IOUT = 0 mA, f = 0	Ind.	_	90	_	90	_	55	
			Auto.	_	_	_	110	_	90	
IsB1	TTL Standby Current	V _{DD} = Max.,	Com.	_	30	_	30	_	30	mA
	(TTL Inputs)	VIN = VIH or VIL	Ind.	_	35	_	35	_	35	
		$\overline{\textbf{CE}} \ge V_{IH}, f = 0$	Auto.	_	_	_	70	_	70	
IsB2	CMOS Standby	V _{DD} = Max.,	Com.	_	20	_	20	_	15	mA
	Current (CMOS Inputs)	$\overline{CE} \ge V_{DD} - 0.2V$,	Ind.	_	25	_	25	_	20	
	. ,	$V_{IN} \ge V_{DD} - 0.2V$, or	Auto.	_	_	_	60	_	60	
		$V_{IN} \leq 0.2V, f = 0$	typ.(2)			4				

^{1.} At $f = f_{MAX}$, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

^{2.} Typical values are measured at VDD = 3.0V, $TA = 25^{\circ}C$ and not 100% tested.



READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

		-	8	-10	0	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
trc	Read Cycle Time	8	_	10	_	ns
taa	Address Access Time	_	8	_	10	ns
t oha	Output Hold Time	2.5	_	2.5	_	ns
tace	CE Access Time	_	8	_	10	ns
t DOE	OE Access Time	_	5.5	_	6.5	ns
THZOE ⁽²⁾	OE to High-Z Output	_	3	_	4	ns
tlzoe(2)	OE to Low-Z Output	0	_	0	_	ns
thzce(2	CE to High-Z Output	0	3	0	4	ns
tlzce(2)	CE to Low-Z Output	3	_	3	_	ns
t BA	LB, UB Access Time	_	5.5	_	6.5	ns
thzb(2)	LB, UB to High-Z Output	0	3	0	3	ns
tlzb(2)	LB, UB to Low-Z Output	0	_	0	_	ns
t pu	PowerUpTime	0	_	0	_	ns
t PD	Power Down Time	_	8	_	10	ns

 $^{1. \ \, \}text{Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.}$

^{2.} Tested with the load in Figure 2. Transition is measured ±500 mV from steady-state voltage.



READ CYCLE SWITCHING CHARACTERISTICS(1) (Over Operating Range)

	-20 ns					
Symbol	Parameter	Min.	Max.	Unit		
t rc	Read Cycle Time	20	_	ns		
taa	Address Access Time	_	20	ns		
tона	Output Hold Time	2.5	_	ns		
tace	CE Access Time	_	20	ns		
tdoe	OE Access Time	_	8	ns		
thzoe(2)	OE to High-Z Output	0	8	ns		
tlzoe(2)	OE to Low-Z Output	0	_	ns		
thzce(2	CE to High-Z Output	0	8	ns		
tLZCE ⁽²⁾	CE to Low-Z Output	3	_	ns		
t BA	LB, UB Access Time	_	8	ns		
t HZB	LB, UB to High-Z Output	0	8	ns		
t LZB	LB, UB to Low-Z Output	0	_	ns		

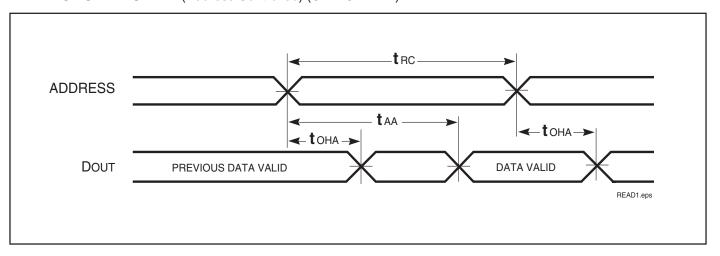
^{1.} Test conditions assume signal transition times of 1.5 ns or less, timing reference levels of 1.25V, input pulse levels of 0.4V to VDD-0.3V and output loading specified in Figure 1a.

^{2.} Tested with the load in Figure 1b. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.

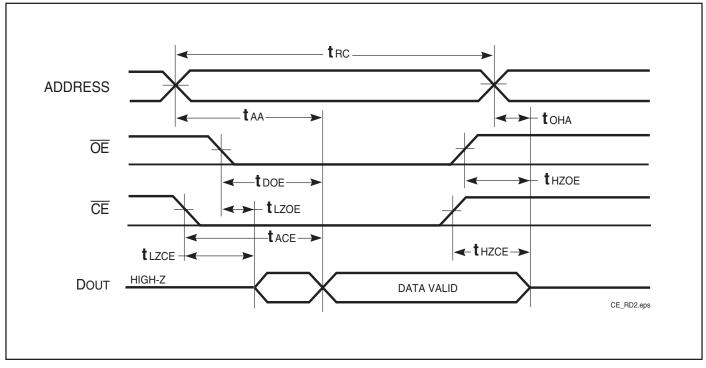
^{3.} Not 100% tested.



AC WAVEFORMS READ CYCLE NO. $1^{(1,2)}$ (Address Controlled) ($\overline{CE} = \overline{OE} = VIL$)



READ CYCLE NO. 2^(1,3) ($\overline{\text{CE}}$ and $\overline{\text{OE}}$ Controlled)



- 1. WE is HIGH for a Read Cycle.
- The device is continuously selected. OE, CE = VIL.
 Address is valid prior to or coincident with CE LOW transitions.



WRITE CYCLE SWITCHING CHARACTERISTICS(1,3) (Over Operating Range)

		-4	3	-10		
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
twc	Write Cycle Time	8	_	10	_	ns
tsce	CE to Write End	6.5	_	8	_	ns
taw	Address Setup Time to Write End	6.5	_	8	_	ns
t HA	Address Hold from Write End	0	_	0	_	ns
t sa	Address Setup Time	0	_	0	_	ns
t PWB	LB, UB Valid to End of Write	6.5	_	8	_	ns
tpwe1	WE Pulse Width	6.5	_	8	_	ns
tpwe2	WE Pulse Width (OE = LOW)	8.0	_	10	_	ns
t sd	Data Setup to Write End	5	_	6	_	ns
tho	Data Hold from Write End	0	_	0	_	ns
thzwe ⁽²⁾	WE LOW to High-Z Output	_	3.5	_	5	ns
tlzwe ⁽²⁾	WE HIGH to Low-Z Output	2	_	2	_	ns

^{1.} Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.

^{2.} Tested with the load in Figure 2. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.

^{3.} The internal write time is defined by the overlap of \overline{CE} LOW and \overline{UB} or \overline{LB} , and \overline{WE} LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write. Shaded are a product in development



WRITE CYCLE SWITCHING CHARACTERISTICS(1,2) (Over Operating Range)

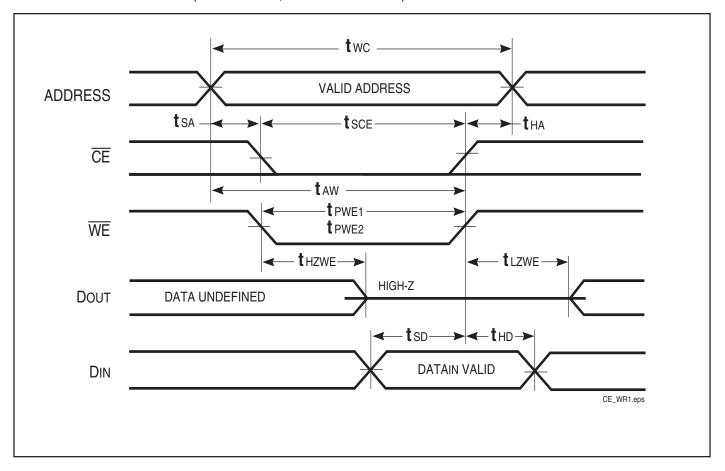
		_	0 ns	
Symbol	Parameter	Min.	Max.	Unit
twc	Write Cycle Time	20	_	ns
tsce	CE to Write End	12	_	ns
taw	Address Setup Time to Write End	12	_	ns
t HA	Address Hold from Write End	0	_	ns
t sa	Address Setup Time	0	_	ns
t PWB	LB, UB Valid to End of Write	12	_	ns
tpwe1	WE Pulse Width (OE = HIGH)	12	_	ns
tpwe2	WE Pulse Width (OE = LOW)	17	_	ns
t sD	Data Setup to Write End	9	_	ns
t HD	Data Hold from Write End	0	_	ns
thzwe ⁽³⁾	WE LOW to High-Z Output	_	9	ns
tLZWE ⁽³⁾	WE HIGH to Low-Z Output	3	_	ns

- Test conditions for IS61WV51216ALL/BLL assume signal transition times of 1.5ns or less, timing reference levels of 1.25V, input pulse levels of 0.4V to Vpp-0.3V and output loading specified in Figure 1a.
- Tested with the load in Figure 1b. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.
- 3. The internal write time is defined by the overlap of $\overline{\textbf{CE}}$ LOW and $\overline{\textbf{UB}}$ or $\overline{\textbf{LB}}$, and $\overline{\textbf{WE}}$ LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.



AC WAVEFORMS

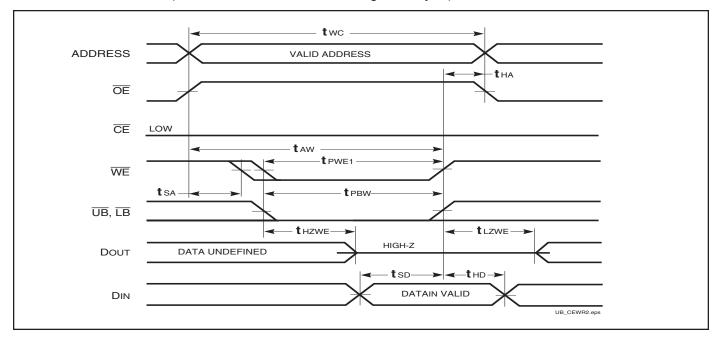
WRITE CYCLE NO. $1^{(1,2)}$ (\overline{CE} Controlled, \overline{OE} = HIGH or LOW)



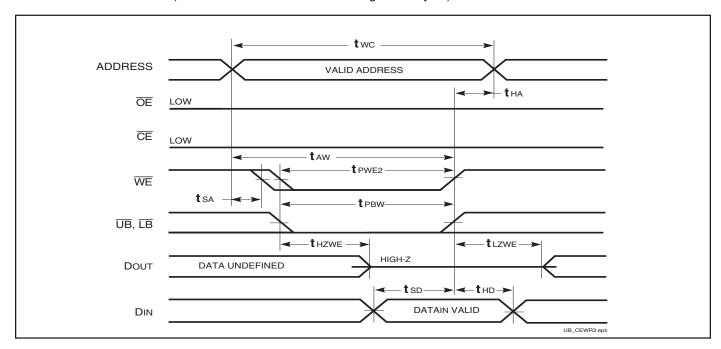


AC WAVEFORMS

WRITE CYCLE NO. 2 (WE Controlled. OE is HIGH During Write Cycle) (1,2)



WRITE CYCLE NO. 3 (WE Controlled. OE is LOW During Write Cycle) (1)

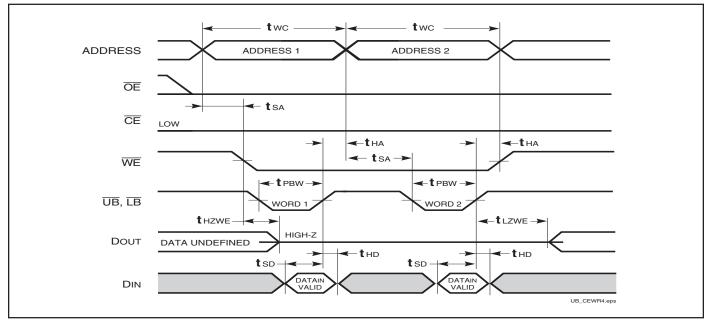


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AC WAVEFORMS

WRITE CYCLE NO. 4 (LB, UB Controlled, Back-to-Back Write) (1,3)



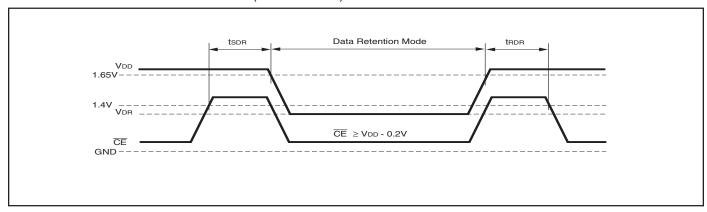
- 1. The internal Write time is defined by the overlap of $\overline{\textbf{CE}} = \texttt{LOW}$, $\overline{\textbf{UB}}$ and/or $\overline{\textbf{LB}} = \texttt{LOW}$, and $\overline{\textbf{WE}} = \texttt{LOW}$. All signals must be in valid states to initiate a Write, but any can be deasserted to terminate the Write. The $\underline{\textbf{t}}_{SA}$, $\underline{\textbf{t}}_{HA}$, $\underline{\textbf{t}}_{SD}$, and $\underline{\textbf{t}}_{HD}$ timing is referenced to the rising or falling edge of the signal that terminates the Write.
- 2. $\underline{\mathsf{Tested}}$ with $\underline{\mathsf{OE}}$ HIGH for a minimum of 4 ns before $\underline{\mathsf{WE}}$ = LOW to place the I/O in a HIGH-Z state.
- 3. WE may be held LOW across many address cycles and the LB, UB pins can be used to control the Write function.



DATA RETENTION SWITCHING CHARACTERISTICS

Symbol	Parameter	Test Condition		Min.	Max.	Unit
VDR	VDD for Data Retention	See Data Retention Waveform		1.2	3.6	V
IDR	Data Retention Current	$V_{DD} = 1.2V, \overline{CE} \ge V_{DD} - 0.2V$	Ind. Auto.		20 50	mA
tsdr	Data Retention Setup Time	See Data Retention Waveform		0	_	ns
trdr	Recovery Time	See Data Retention Waveform		trc	_	ns

DATA RETENTION WAVEFORM (CE Controlled)





ORDERING INFORMATION

Industrial Range: -40°C to +85°C Voltage Range: 2.4V to 3.6V

Speed (ns)	Order Part No.	Package
10 (8¹)	IS61WV51216BLL-10MI	48 mini BGA (9mm x 11mm)
	IS61WV51216BLL-10MLI	48 mini BGA (9mm x 11mm), Lead-free
	IS61WV51216BLL-10TI	TSOP (Type II)
	IS61WV51216BLL-10TLI	TSOP (Type II), Lead-free

Note:

Industrial Range: -40°C to +85°C Voltage Range: 1.65V to 2.2V

Speed (ns)	Order Part No.	Package
20	IS61WV51216ALL-20MI	48 mini BGA (9mm x 11mm)
	IS61WV51216ALL-20TI	TSOP (Type II)

Automotive Range: -40°C to +125°C

Voltage Range: 2.4V to 3.6V

Speed (ns)	Order Part No.	Package
10	IS64WV51216BLL-10MA3	48 mini BGA (9mm x 11mm)
	IS64WV51216BLL-10MLA3	48 mini BGA (9mm x 11mm), Lead-free
	IS64WV51216BLL-10CTA3	TSOP (Type II), Copper Leadframe
	IS64WV51216BLL-10CTLA3	TSOP (Type II), Lead-free, Copper Leadframe

^{1.} Speed = 8ns for V_{DD} = 3.3V \pm 5%. Speed = 10ns for V_{DD} = 2.4V - 3.6V



